Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)

Contact Info:

ti.com/support
Distribute - RoHS and IEC 62474 DB Form/Declaration Type:

05/30/2022 Created on:

Details for "DS92LX1622SQX/NOPB"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
DS92LX1622SQX/NOPB	SN	Level-3-260C-168 HR	Texas Instruments Electronics	RTA 40	6 x 6 x 0.75	105.8

*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

ſ	RoHS	REACH	Green	IEC 62474 DB
ſ	Yes	Yes	Yes	Yes

Component Information

				Homogeneous Material Level		Component Level	
Component	Substance	CAS Number	Amount (mg)	Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.384728	97.535055	975351	0.363733	363
Nickel and Its Alloys	Nickel	7440-02-0	0.000002	0.000507	5	0.000002	
Not Categorized	Proprietary Materials		0.000043	0.010901	109	0.000041	
Precious Metals	Gold	7440-57-5	0.000203	0.051464	515	0.000192	
Precious Metals	Palladium	7440-05-3	0.009464	2.399284	23993	0.008948	8
Precious Metals	Silver	7440-22-4	0.000011	0.002789	28	0.00001	
Sub-Total			0.394451	100	1000000	0.372926	372
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.847129	75.000022	750000	0.800901	800
Thermoplastics	Epoxy	85954-11-6	0.282376	24.999978	250000	0.266967	267
Sub-Total			1.129505	100	1000000	1.067868	1067
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	61.99578	97.02	970200	58.612676	58612
Copper and Its Alloys	Iron	7439-89-6	1.6614	2.6	26000	1.570738	1570
Copper and Its Alloys	Phosphorus	7723-14-0	0.09585	0.15	1500	0.090619	90
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.01917	0.03	300	0.018124	18
Zinc and Its Alloys	Zinc	7440-66-6	0.1278	0.2	2000	0.120826	120
Sub-Total			63.9	100	1000000	60.412983	60413
Lead Frame Plating							
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.4	100	1000000	0.378172	378
Sub-Total			0.4	100	1000000	0.378172	378
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	33.582973	90.500001	905000	31.750353	31750
Thermoplastics	Ероху	85954-11-6	3.525284	9.499999	95000	3.33291	3332
Sub-Total			37.108257	100	1000000	35.083263	35083
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	2.839753	100	1000000	2.684788	2684
Sub-Total			2.839753	100	1000000	2.684788	2684
Total			105,771966			100	100000

Important Note

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component See Glossary of Terms for more details.

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology
For an explanation of the methods used to determine material weights, See Product Content Methodology

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is." For additional information, please contact TI customer support.

Signature: (click here for a fuller statement with a signed certificate)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality For further environmental statements, please go to www.ti.com/ecoinfo Created on: 05/30/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

ROHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in http://www.ti.com/lit/pdf/szqq088

Green: Means the content of Chiorine (CI) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb203) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.